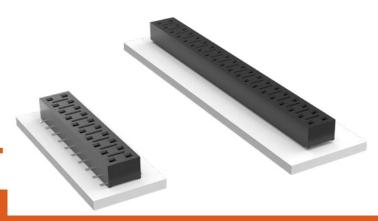


COST-EFFECTIVE ELIABLE SOCK

(2.54 mm) .100" PITCH • HLE SERIES



HLE **Board Mates:**

TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

NO. PINS PER ROW HLE

02 thru 50

П П Д.

PLATING OPTION

Gold flash on

contact, Matte Tin on tail

= 10 μ" (0.25 μm)

Gold on contact,

Matte Tin on tail

TAIL OPTION

OTHER OPTION -BE

Bottom Entry

Leave blank for

(Requires –BE for Bottom Entry)

Surface Mount

-TE = Through-hole Top Entry

-PE

= Through-hole Pass-through Entry (Requires –BE for Bottom Entry) (Not available with –TE)

-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (Not available with -TE, -PE & -LC)

-LC

= Locking Clip (2 positions min.) (Not available with -A) (Manual placement required)

> **-K** = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad

(3 positions min.) Not available with -TE or -PE tail option

-P

= Metal Pick & Place Pad (3 positions min.)

-TR

= Tape & Reel (29 positions max.)

-FR

= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

SPECIFICATIONS

Insulator Material: Black Liquid Crystal Polymer Contact Material:

Plating:
Au or Sn over
50 µ" (1.27 µm) Ni
Current Rating (HLE/TSM): 4.1 A per pin

(2 pins powered) **Voltage Rating:** 400 VAC

Operating Temp Range: -55 °C to +125 °C

Insertion Depth:

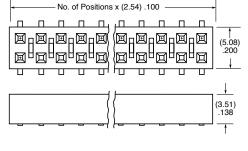
(1.78 mm) .070" to (3.43 mm) .135" pass-through, or (2.59 mm) .102" min plus board thickness for bottom entry

PROCESSING

Lead-Free Solderable:

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-20) (0.15 mm) .006" max (21-50)* *(.004" stencil solution may be available; contact ipg@samtec.com)



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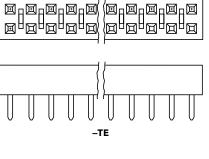




(7.62) .300

ALSO AVAILABLE MOQ Required

Other Platings











F-224

Some lengths, styles and options are non-standard, non-returnable.